

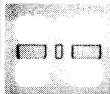

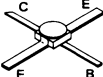


Advance Information
The RF Line
NPN Silicon
Low Noise, High-Frequency,
Transistors

MRF941
MRFC941
MRF942
MMBR941,L
MRF9411,L

$I_C = 15$ mA
LOW NOISE
HIGH FREQUENCY
TRANSISTORS

... designed for use in low noise, small-signal amplifiers. This series features low noise, high gain, and current capability offered in a variety of packages.

- Fully Implanted Base and Emitter Structure
- 9 Finger, 1.25 Micron Geometry with Gold Top Metal
- Gold Sintered Back Metal
- Tape and Reel packaging Options Available

		MRFC941	MRF941	MRF942	MMBR941,L	MRF9411,L	
							
MAXIMUM RATINGS		Chip	Macro-X Case 317-01	Case 303-01	SOT-23 Case 318-02	Case 318B-01 (SOT-143)	
Ratings	Symbol	Values					Unit
Collector-Emitter Voltage	V_{CE0}	10	10	10	10	10	Vdc
Collector-Base Voltage	V_{CB0}	20	20	20	20	20	Vdc
Emitter-Base Voltage	V_{EBO}	1.5	1.5	1.5	1.5	1.5	Vdc
Maximum Junction Temperature	T_{Jmax}	200	150	200	150	150	°C
Collector Current — Continuous ⁽³⁾	I_C	15	50	15	50	50	mA
Storage Temperature	T_{stg}	-65 to +200	-65 to +150	-65 to +200	-55 to +150	-65 to +150	°C

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Collector-Emitter Breakdown Voltage ($I_C = 0.1$ mA, $I_B = 0$)	$V_{(BR)CEO}$	10	13	—	Vdc
Collector-Base Breakdown Voltage ($I_C = 0.1$ mA, $I_E = 0$)	$V_{(BR)CBO}$	20	25	—	Vdc
Emitter Cutoff Current ($V_{EB} = 1$ V, $I_E = 0$)	I_{EBO}	—	—	1	μ Adc
Collector Cutoff Current ($V_{CB} = 10$ V, $I_E = 0$)	I_{CBO}	—	—	1	μ Adc

ON CHARACTERISTICS

DC Current Gain ($V_{CE} = 6$ V, $I_C = 5$ mA)	h_{FE}	50	—	200	—
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Note 1. Case Temperature is measured on the collector lead where it first contacts the printed circuit board closest to the package.

Note 2. Device offered in other ceramic/plastic packages.

Note 3. I_C — Continuous (MTBF = 10 years)

(continued)

MRF941 Series

ELECTRICAL CHARACTERISTICS — continued ($T_C = 25^\circ\text{C}$ unless otherwise noted.)

Characteristic	Symbol	Min	Typ	Max	Unit
DYNAMIC CHARACTERISTICS					
Collector-Base Capacitance ($V_{CB} = 10\text{ V}, I_E = 0, f = 1\text{ MHz}$)	C_{cb}	—	0.2	—	pF
Current Gain — Bandwidth Product ($V_{CE} = 6\text{ V}, I_C = 15\text{ mA}, f = 1\text{ GHz}$)	f_T	—	8	—	GHz
FUNCTIONAL TESTS					
Associated Gain at Minimum Noise Figure ($V_{CE} = 6\text{ V}, I_C = 5\text{ mA}, f = 1\text{ GHz}$) ($V_{CE} = 6\text{ V}, I_C = 5\text{ mA}, f = 2\text{ GHz}$) ($V_{CE} = 6\text{ V}, I_C = 5\text{ mA}, f = 4\text{ GHz}$)	G_{NF}	— — —	16.5 12.5 9	— — —	dB
Noise Figure ($V_{CE} = 6\text{ V}, I_C = 5\text{ mA}, f = 1\text{ GHz}$) ($V_{CE} = 6\text{ V}, I_C = 5\text{ mA}, f = 2\text{ GHz}$) ($V_{CE} = 6\text{ V}, I_C = 5\text{ mA}, f = 4\text{ GHz}$)	NF_{min}	— — —	1.2 1.7 2.8	— — —	dB

TYPICAL CHARACTERISTICS

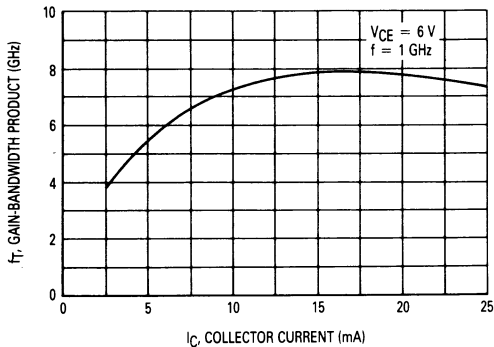


Figure 1. Gain-Bandwidth Product versus Current

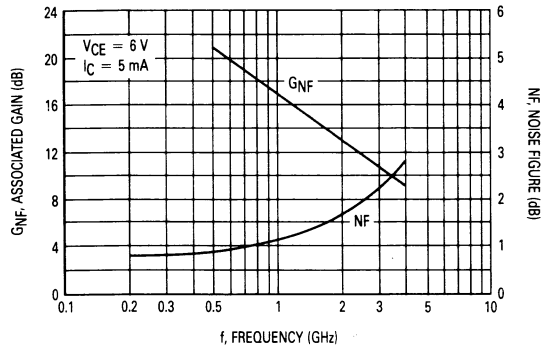


Figure 2. Associated Gain and Optimum Noise Figure versus Frequency

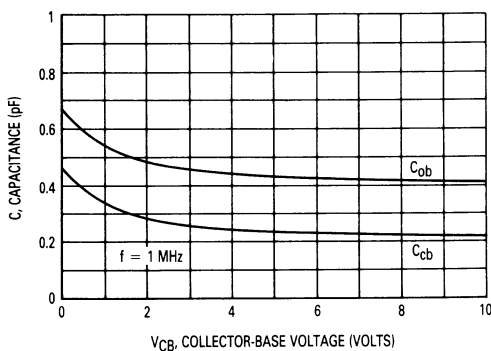


Figure 3. Junction Capacitance versus Voltage

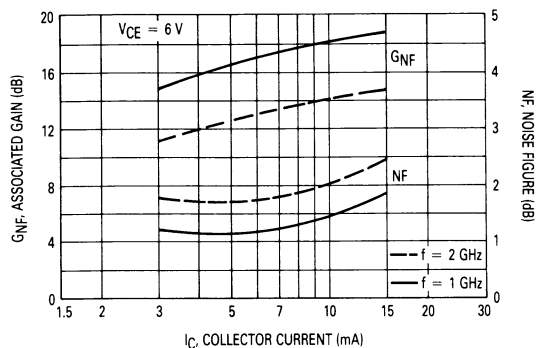


Figure 4. Associated Gain and Optimum Noise Figure versus Collector Current

Advance Information

The RF Line






NPN Silicon
Low Noise, High-Frequency
Transistors

MRF951
MRFC951
MRF952
MMBR951,L
MRF9511,L

... designed for use in high gain, low noise small-signal amplifiers. This series features excellent broadband linearity and is offered in a variety of packages.

- Fully Implanted Base and Emitter Structure
- 18 Finger, 1.25 Micron Geometry with Gold Top Metal
- Gold Sintered Back Metal
- Tape and Reel Packaging Options Available

I_C = 30 mA
LOW NOISE
HIGH FREQUENCY
TRANSISTORS

		MRFC951	MRF951	MRF952	MMBR951,L	MRF9511,L	
MAXIMUM RATINGS		 Chip	 Macro-X Case 317-01	 Case 303-01	 SOT-23 Case 318-02	 Case 318B-01 (SOT-143)	
Ratings	Symbol	Values					Unit
Collector-Emitter Voltage	V _{CEO}	10	10	10	10	10	V _{dc}
Collector-Base Voltage	V _{CBO}	20	20	20	20	20	V _{dc}
Emitter-Base Voltage	V _{EBO}	1.5	1.5	1.5	1.5	1.5	V _{dc}
Maximum Junction Temperature	T _{Jmax}	200	150	200	150	150	°C
Collector Current — Continuous ⁽³⁾	I _C	30	100	30	100	100	mA
Storage Temperature	T _{stg}	-65 to +200	-65 to +150	-65 to +200	-55 to +150	-65 to +150	°C

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Collector-Emitter Breakdown Voltage (I _C = 0.1 mA, I _B = 0)	V _{(BR)CEO}	10	13	—	V _{dc}
Collector-Base Breakdown Voltage (I _C = 0.1 mA, I _E = 0)	V _{(BR)CBO}	20	25	—	V _{dc}
Emitter Cutoff Current (V _{EB} = 1 V, I _E = 0)	I _{EBO}	—	—	1	μA _{dc}
Collector Cutoff Current (V _{CB} = 10 V, I _E = 0)	I _{CBO}	—	—	1	μA _{dc}

ON CHARACTERISTICS

DC Current Gain (V _{CE} = 6 V, I _C = 5 mA)	h _{FE}	50	—	200	—
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Note 1. Case Temperature is measured on the collector lead where it first contacts the printed circuit board closest to the package.

Note 2. Device offered in other ceramic/plastic packages.

Note 3. I_C — Continuous (MTBF = 10 years)

(continued)

MRF951 Series

ELECTRICAL CHARACTERISTICS — continued ($T_C = 25^\circ\text{C}$ unless otherwise noted.)

Characteristic	Symbol	Min	Typ	Max	Unit
DYNAMIC CHARACTERISTICS					
Collector-Base Capacitance ($V_{CB} = 10\text{ V}, I_E = 0, f = 1\text{ MHz}$)	C_{cb}	—	0.3	—	pF
Current Gain — Bandwidth Product ($V_{CE} = 6\text{ V}, I_C = 30\text{ mA}, f = 1\text{ GHz}$)	f_T	—	7.5	—	GHz
FUNCTIONAL TESTS					
Associated Gain at Minimum ($V_{CE} = 6\text{ V}, I_C = 5\text{ mA}, f = 1\text{ GHz}$) ($V_{CE} = 6\text{ V}, I_C = 5\text{ mA}, f = 2\text{ GHz}$)	G _{NF}	— —	16.5 12.5	— —	dB
Noise Figure ($V_{CE} = 6\text{ V}, I_C = 5\text{ mA}, f = 1\text{ GHz}$) ($V_{CE} = 6\text{ V}, I_C = 5\text{ mA}, f = 2\text{ GHz}$)	N _{Fmin}	— —	1.2 1.7	— —	dB

TYPICAL CHARACTERISTICS

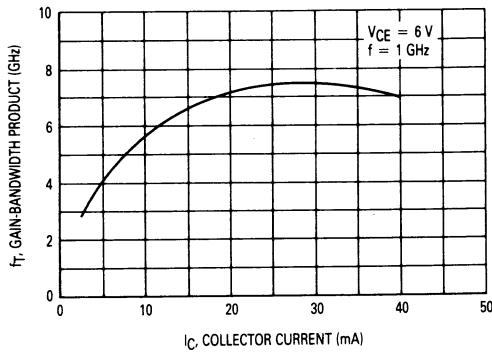


Figure 1. Gain-Bandwidth Product versus Current

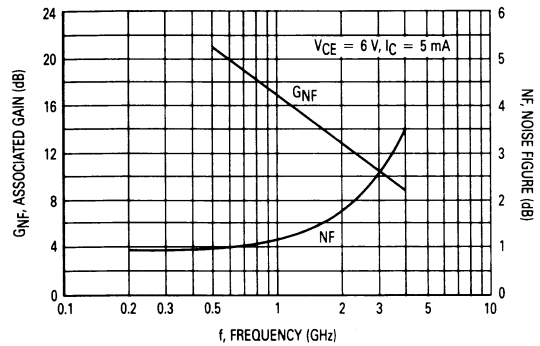


Figure 2. Associated Gain and Optimum Noise Figure versus Frequency

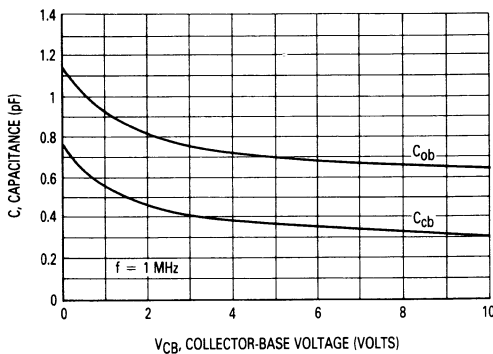


Figure 3. Junction Capacitance versus Voltage

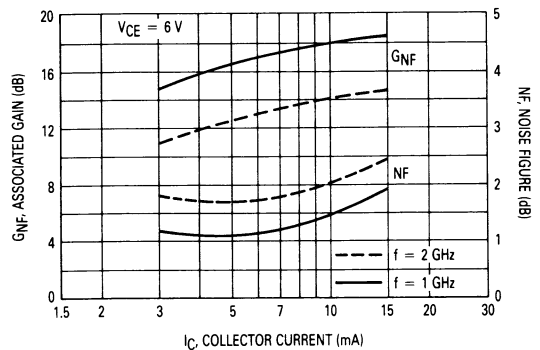


Figure 4. Associated Gain and Optimum Noise Figure versus Collector Current

The RF Line
N-Channel Dual-Gate GaAs
Field-Effect Transistor

... depletion mode dual-gate MES FET designed for high frequency amplifier and mixer applications.

- Excellent Receiver Front End
- Low Noise Figure — NF = 1.2 dB, 1 GHz (Typ)
- High Power Gain — $G_p = 17$ dB, 1 GHz (Typ)
- Low Reverse Transfer Capacitance — $C_{rss} = 40$ fF (Typ)
- High Transconductance — $g_m = 20$ mS (Typ)
- Fully Characterized
- Gold Metallization

MAXIMUM RATINGS

Rating	Symbol	MRFC966	MRF966	Unit
Drain-Source Voltage	V_{DS}	10	10	Vdc
Gate-Source Voltage — Reverse	V_{G1S} V_{G2S}	-8 -8	-8 -8	Vdc
Gate-Source Voltage — Forward	V_{G1S} V_{G2S}	+1 +1	+1 +1	Vdc
Drain Current — Continuous	I_D	80	80	mAdc
Total Power Dissipation ($T_A = 25^\circ\text{C}$ Derate above 25°C)	P_D	350 $T_J = 125^\circ\text{C Max}$	350 3.5	mW mW/ $^\circ\text{C}$
Storage Channel Temperature Range	T_{stg}	-65 to +125	-65 to +125	$^\circ\text{C}$
Junction Temperature Range	T_J	-65 to +125	-65 to +125	$^\circ\text{C}$

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted.)

Characteristic	Symbol	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Drain-Source Breakdown Voltage ($V_{G1S} = V_{G2S} = -4.5$ Vdc, $I_D = 100$ μA)	$V_{(BR)DSX}$	10	—	—	Vdc
Gate 1-to-Source Cutoff Voltage ($V_{DS} = 5$ Vdc, $V_{G2S} = 0$, $I_D = 500$ μA)	$V_{G1S(off)}$	-2	—	-4.5	Vdc
Gate 2-to-Source Cutoff Voltage ($V_{DS} = 5$ Vdc, $V_{G1S} = 0$, $I_D = 500$ μA)	$V_{G2S(off)}$	-2	—	-4.5	Vdc
Gate 1 Leakage Current ($V_{G1S} = -5$ Vdc, $V_{G2S} = V_{DS} = 0$)	I_{G1SS}	—	—	10	μAdc
Gate 2 Leakage Current ($V_{G2S} = -5$ Vdc, $V_{G1S} = V_{DS} = 0$)	I_{G2SS}	—	—	10	μAdc

ON CHARACTERISTICS

Zero-Gate Voltage Drain Current ($V_{DS} = 5$ Vdc, $V_{G1S} = V_{G2S} = 0$)	I_{DSS}	30	50	80	mAdc
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SMALL-SIGNAL CHARACTERISTICS

Transconductance ($V_{DS} = 5$ Vdc, $V_{G2S} = 0$, $I_D = 10$ mA, $f = 1$ kHz)	g_m	18	20	—	mS
Input Capacitance ($V_{DS} = 5$ Vdc, $V_{G2S} = 0$, $I_D = 10$ mA, $f = 1$ MHz)	C_{iss}	—	1.5	—	pF
Reverse Transfer Capacitance ($V_{DS} = 5$ Vdc, $V_{G2S} = 0$, $I_D = 10$ mA, $f = 1$ MHz)	C_{rss}	—	0.04	—	pF

Handling and Packaging — MES devices are susceptible to damage from electrostatic charge. Reasonable precautions in handling and packaging MES devices should be observed.

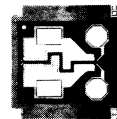
(continued)

MRF966
MRFC966

N-CHANNEL
DUAL-GATE
GaAs FIELD-EFFECT
TRANSISTOR



MRF966
CASE 317-01



CHIP
MRFC966

ELECTRICAL CHARACTERISTICS — continued (T_A = 25°C unless otherwise noted.)

Characteristic	Symbol	Min	Typ	Max	Unit
FUNCTIONAL CHARACTERISTICS					
Noise Figure(1) (V _{DS} = 5 Vdc, V _{G2S} = 0, I _{DS} = 10 mA, f = 1 GHz)	NF	—	1.2	1.5	dB
Common Source Power Gain(1) (V _{DS} = 5 Vdc, V _{G2S} = 0, I _{DS} = 10 mA, f = 1 GHz)	G _{ps}	15	17	—	dB
Intermodulation Distortion (V _{DS} = 5 Vdc, I _{DS} = 10 mA, f ₁ = 995 MHz, f ₂ = 1001 MHz, V _{G2} = 0, P _{in} = -40 dBm)	IMD ₃	—	-65	—	dB
Linear Power Point(2) (V _{DS} = 5 Vdc, I _{DS} = 10 mA, f ₁ = 995 MHz, f ₂ = 1001 MHz, V _{G2} = 0)	PL	—	+1	—	dBm
Output Power at 1 dB Compression Point (V _{DS} = 5 Vdc, I _{DS} = 10 mA, f = 1 GHz)	P _{out}	—	10	—	dBm

NOTES:

- Data taken using a 50 Ω test fixture, Microlab SF31N slug tuners, HP11590B bias networks and the HP8970A or Eaton 2075 noise figure meter.
Note: V_{G2S} = 0. Refer to Figure 11.
- The linear power point is the output power level at which either the signal 2f₁ ± f₂ or 2f₂ ± f₁ are 30 dB below f₁ or f₂.

TYPICAL CHARACTERISTICS

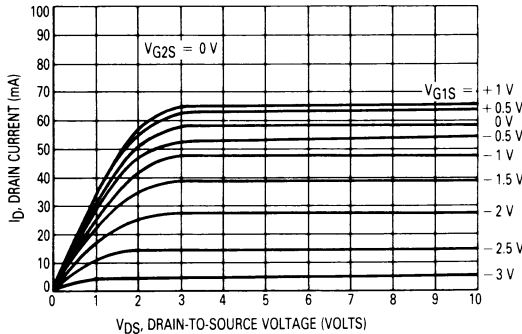


Figure 1. Drain Current versus Drain-To-Source Voltage

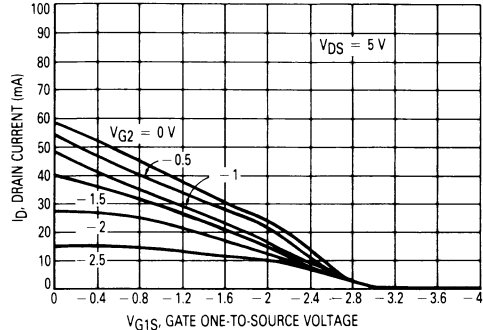


Figure 2. Drain Current versus Gate One-To-Source Voltage

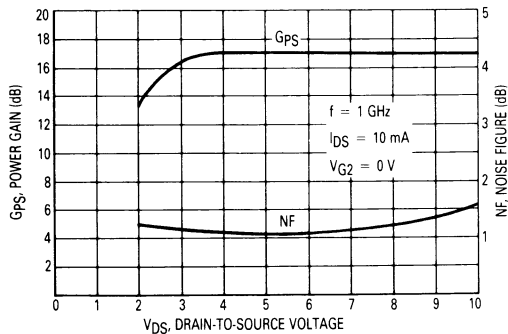


Figure 3. Power Gain and Noise Figure versus Drain-To-Source Voltage

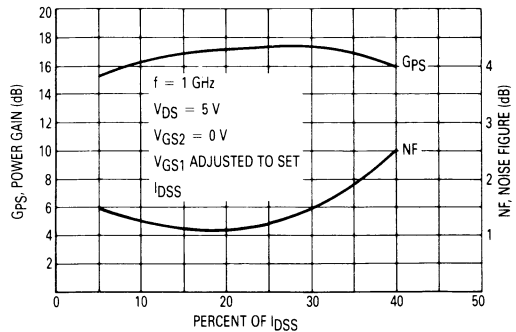


Figure 4. Power Gain and Noise Figure versus Percent of I_{DS}

TYPICAL CHARACTERISTICS

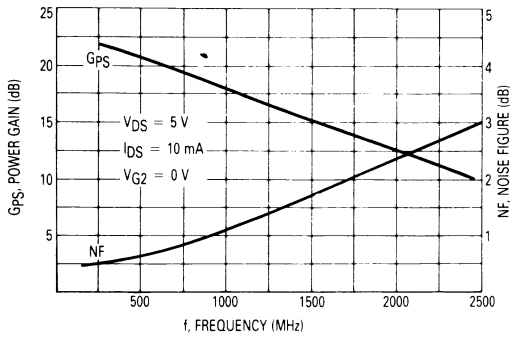


Figure 5. Power Gain and Noise Figure versus Frequency

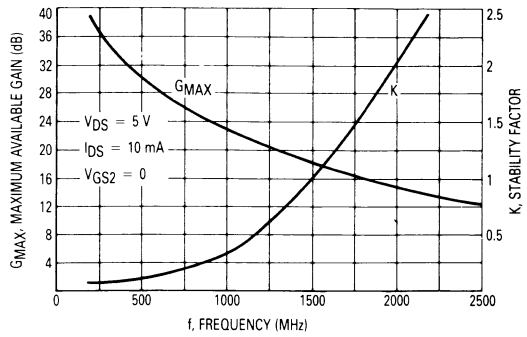


Figure 6. Maximum Available Gain and Stability Factor versus Frequency

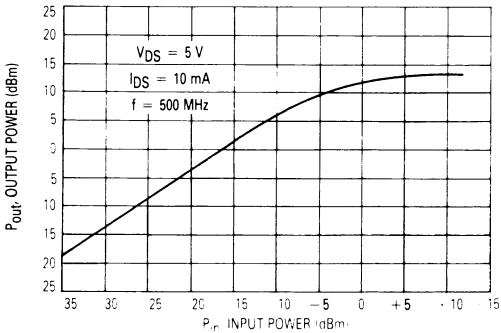


Figure 7. Output Power versus Input Power @ 500 MHz

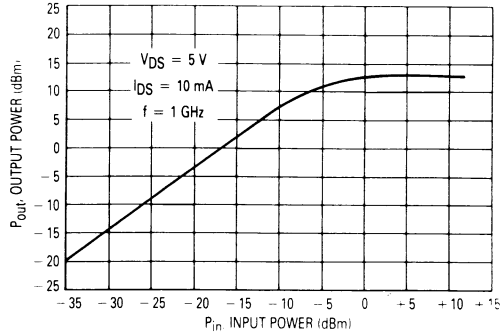


Figure 8. Output Power versus Input Power @ 1 GHz

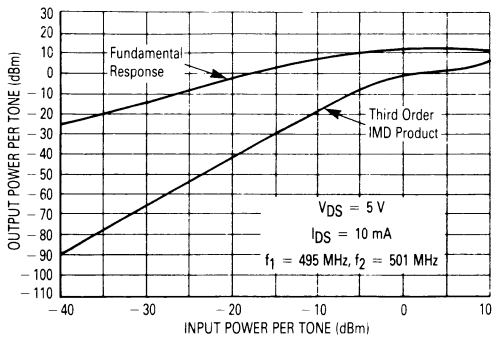


Figure 9. Third Order Intermodulation Distortion @ 500 MHz

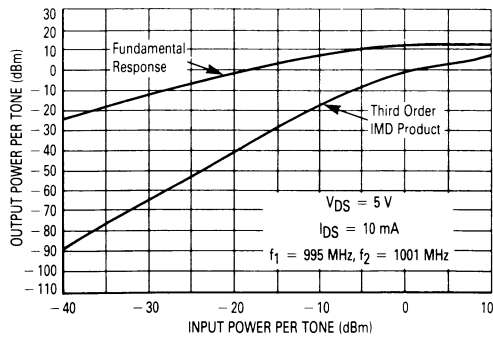


Figure 10. Third Order Intermodulation Distortion @ 1 GHz

COMMON SOURCE S-PARAMETERS

V _{DS} (Volts)	I _{DS} (mA)	f (MHz)	S ₁₁		S ₂₁		S ₁₂		S ₂₂	
			S ₁₁	∠φ	S ₂₁	∠φ	S ₁₂	∠φ	S ₂₂	∠φ
3	5	200	0.997	-5.7	1.251	172.1	0.003	88.3	0.944	-6.4
		500	0.983	-14.3	1.23	161.2	0.007	84.6	0.931	-16
		1000	0.941	-28.3	1.201	142.4	0.013	78.5	0.9	-32.2
		1500	0.866	-42.3	1.133	122	0.016	70.4	0.836	-49.6
		2000	0.762	-55.4	1.011	101.1	0.018	56.2	0.744	-67.5
	2500	0.642	-66.4	0.819	77.4	0.015	25.5	0.608	-87.5	
	10	200	0.995	-6.2	1.60	172.0	0.002	84.1	0.93	-6.3
		500	0.981	-15.1	1.58	161.3	0.007	82.5	0.92	-15.8
		1000	0.928	-29.9	1.55	142.9	0.013	81.5	0.90	-31.8
		1500	0.838	-44.4	1.46	122.3	0.016	74.7	0.84	-49.4
		2000	0.716	-57.7	1.31	101.2	0.018	60.1	0.76	-68.4
	2500	0.584	-67.5	1.06	77.4	0.015	26.7	0.63	-89.8	
	15	200	0.996	-6.3	1.83	172.0	0.002	76.4	0.93	-6.3
		500	0.979	-15.7	1.80	161.2	0.006	91.5	0.92	-15.6
		1000	0.921	-30.9	1.76	142.3	0.012	82.3	0.90	-31.6
		1500	0.820	-45.9	1.66	121.7	0.016	76.1	0.85	-49.1
		2000	0.689	-58.7	1.48	100.6	0.016	64.1	0.77	-68.2
	2500	0.552	-67.4	1.20	76.7	0.013	28.9	0.65	-90.3	
	20	200	0.995	-6.5	1.97	171.9	0.003	85.7	0.92	-6.2
		500	0.977	-16.2	1.93	160.7	0.007	89.0	0.91	-15.3
1000		0.910	-32.0	1.89	141.7	0.011	84.0	0.89	-31.0	
1500		0.804	-47.1	1.79	120.9	0.016	78.3	0.85	-48.4	
2000		0.669	-59.7	1.59	99.6	0.017	66.2	0.78	-67.4	
2500	0.531	-67.7	1.29	75.8	0.012	32.7	0.66	-89.2		
5	5	200	0.997	-5.8	1.27	172.8	0.002	102.6	0.97	-3.8
		500	0.983	-14.3	1.26	162.6	0.004	82.3	0.97	-9.4
		1000	0.939	-28.4	1.24	146.0	0.006	93.4	0.96	-18.8
		1500	0.866	-42.6	1.21	128.4	0.008	102.6	0.95	-28.3
		2000	0.765	-5.3	1.14	111.6	0.007	137.7	0.93	-37.6
	2500	0.642	-68.4	1.05	93.1	0.012	-179.0	0.92	-47.0	
	10	200	0.966	-6.0	1.61	172.8	0.002	88.1	0.97	-3.8
		500	0.982	-15.1	1.59	162.8	0.004	85.8	0.97	-9.4
		1000	0.928	-29.9	1.57	146.1	0.006	94.6	0.96	-18.6
		1500	0.841	-44.6	1.53	128.7	0.006	110.4	0.94	-28.0
		2000	0.724	-58.3	1.42	111.6	0.008	152.6	0.93	-37.0
	2500	0.589	-69.4	1.30	93.3	0.014	179.1	0.92	-46.3	
	15	200	0.997	-6.2	1.82	172.6	0.001	103.2	0.97	-3.7
		500	0.979	-15.6	1.80	162.5	0.003	85.3	0.96	-9.3
		1000	0.920	-30.8	1.77	145.6	0.005	92.4	0.95	-18.4
		1500	0.824	-45.8	1.72	127.9	0.007	116.3	0.94	-27.3
		2000	0.699	-59.2	1.59	110.8	0.008	154.1	0.93	-36.3
	2500	0.560	-69.6	1.44	92.6	0.017	176.2	0.92	-45.4	
	20	200	0.995	-6.5	1.96	172.4	0.002	85.9	0.97	-3.7
		500	0.977	-16.1	1.93	162.1	0.004	80.9	0.96	-9.1
1000		0.913	-31.7	1.90	144.9	0.005	92.1	0.95	-17.9	
1500		0.810	-47.0	1.83	126.9	0.007	121.4	0.94	-26.9	
2000		0.679	-60.4	1.69	109.7	0.009	153.4	0.93	-35.6	
2500	0.538	-70.0	1.53	91.4	0.017	176.0	0.93	-44.6		

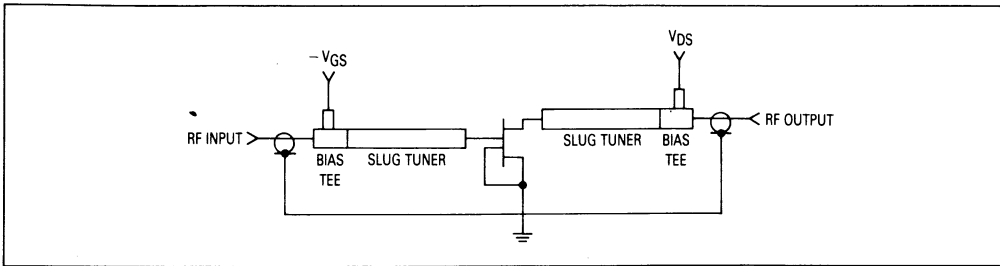
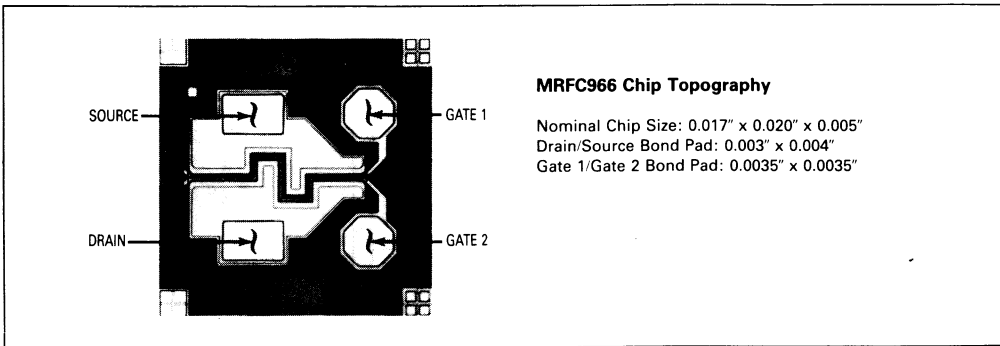


Figure 11. 1 GHz Test Circuit Schematic

f (MHz)	G _{NF} (dB)	NF (dB)	$\Gamma_{MS} NF_{opt}$	$\Gamma_{ML} NF_{opt}$
450	20	0.6	0.82 /21°	0.80 /11°
1000	17	1.2	0.74 /21°	0.77 /12°

Figure 12. Source and Load Impedance for Optimum Noise Figure



3

OUTLINE DIMENSIONS

